Quad OR/NOR Gate

Description

The MC10H101 is a quad 2-input OR/NOR gate with one input from each gate common to pin 12. This MECL $10H^{\text{TM}}$ part is a functional/pinout duplication of the standard MECL $10K^{\text{TM}}$ family part, with 100% improvement in propagation delay, and no increases in power-supply current.

Features

- Propagation Delay, 1.0 ns Typical
- Power Dissipation 25 mW/Gate (same as MECL 10K)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible
- Pb-Free Packages are Available*



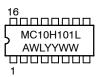
ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS*



CDIP-16 L SUFFIX CASE 620



MC10H101P ○ AWLYYWWG

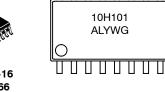
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PDIP-16 P SUFFIX CASE 648

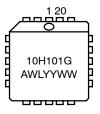


SOEIAJ-16 CASE 966





PLLC-20 FN SUFFIX CASE 775



A = Assembly Location

WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

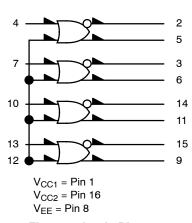
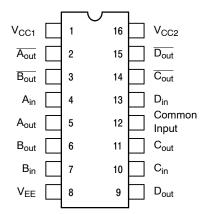


Figure 1. Logic Diagram



Pin assignment is for Dual-in-Line Package.

Figure 2. Pin Assignment

Table 1. MAXIMUM RATINGS

| Symbol | Characteristic | | Rating | Unit |
|------------------|-------------------------------------|---------------------|----------------------------|----------|
| V _{EE} | Power Supply (V _{CC} = 0) | | -8.0 to 0 | Vdc |
| VI | Input Voltage (V _{CC} = 0) | | 0 to V _{EE} | Vdc |
| l _{out} | Output Current | Continuous Surge | 50 100 | mA |
| T _A | Operating Temperature Range | | 0 to +75 | °C |
| T _{stg} | Storage Temperature Range | Plastic Ceramic | −55 to +150 −55 to +165 | °C °C |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS (V_{EE} = -5.2 V $\pm 5\%$) (Note 1)

| | | 0 ° | | 25° | | 75 ° | | |
|------------------|----------------------------------|------------|------------|--------|------------|-------------|------------|------|
| Symbol | Characteristic | Min | Max | Min | Max | Min | Max | Unit |
| Ι _Ε | Power Supply Current | = | 29 | - | 26 | - | 29 | mA |
| I _{inH} | Input Current High (Pin 12 only) | - - | 425 850 | - - | 265 535 | - - | 265 535 | μΑ |
| I _{inL} | Input Current Low | 0.5 | - | 0.5 | _ | 0.3 | _ | μΑ |
| V _{OH} | High Output Voltage | -1.02 | -0.84 | -0.98 | -0.81 | -0.92 | -0.735 | Vdc |
| V _{OL} | Low Output Voltage | -1.95 | -1.63 | -1.95 | -1.63 | -1.95 | -1.60 | Vdc |
| V _{IH} | High Input Voltage | -1.17 | -0.84 | -1.13 | -0.81 | -1.07 | -0.735 | Vdc |
| V _{IL} | Low Input Voltage | -1.95 | -1.48 | -1.95 | -1.48 | -1.95 | -1.45 | Vdc |

Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50 Ω resistor to -2.0 V.

Table 3. AC PARAMETERS

| | | | 0 ° | | 25° | | 75° | | |
|-----------------|-------------------|-------------------------------|------------|-------------|------------|------------|------------|------------|------|
| Symbol | Characteristic | | Min | Max | Min | Max | Min | Max | Unit |
| t _{pd} | Propagation Delay | Pin 12 Only Exclude Pin 12 | 0.5 0.5 | 1.6 1.45 | 0.5 0.5 | 1.6 1.5 | 0.5 0.5 | 1.7 1.6 | ns |
| t _r | Rise Time | | 0.5 | 2.1 | 0.5 | 2.2 | 0.5 | 2.3 | ns |
| t _f | Fall Time | | 0.5 | 2.1 | 0.5 | 2.2 | 0.5 | 2.3 | ns |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

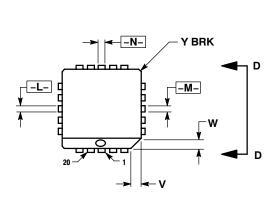
ORDERING INFORMATION

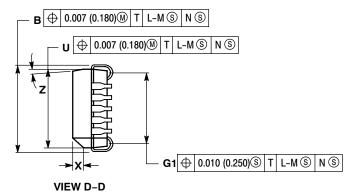
| Device | Package | Shipping [†] |
|---------------|------------------------|-----------------------|
| MC10H101M | SOEIAJ-16 | 50 Unit / Rail |
| MC10H101MG | SOEIAJ-16 (Pb-Free) | 50 Unit / Rail |
| MC10H101MEL | SOEIAJ-16 | 2000 / Tape & Reel |
| MC10H101MELG | SOEIAJ-16 (Pb-Free) | 2000 / Tape & Reel |
| MC10H101FN | PLLC-20 | 46 Units / Rail |
| MC10H101FNG | PLLC-20 (Pb-Free) | 46 Units / Rail |
| MC10H101FNR2 | PLLC-20 | 500 / Tape & Reel |
| MC10H101FNR2G | PLLC-20 (Pb-Free) | 500 / Tape & Reel |
| MC10H101L | CDIP-16 | 25 Unit / Rail |
| MC10H101P | PDIP-16 | 25 Unit / Rail |
| MC10H101PG | PDIP-16 (Pb-Free) | 25 Unit / Rail |

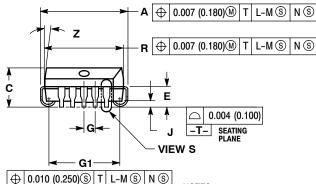
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

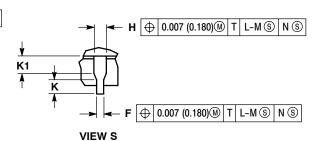
PACKAGE DIMENSIONS

20 LEAD PLLC CASE 775-02 **ISSUE E**









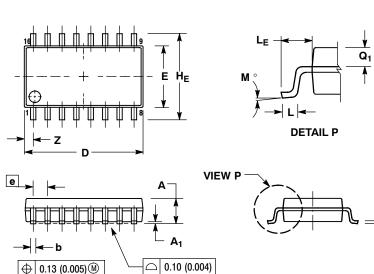
- NOTES:
 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. DIMENSIONS IN INCHES.
 3. DATUMS -L., -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

- PARTING LINE.
 4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM —T-, SEATING PLANE.
 5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- PLASTIC BODY.
 7. DIMENSION H DOES NOT INCLUDE DAMBAR DIMIENSION H DUES NOT INCLUDE DAMBAR
 PROTRUSION OR INTRUSION. THE DAMBAR
 PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION
 TO BE GREATER THAN 0.037 (0.940). THE DAMBAR
 INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO
 BE SMALLER THAN 0.025 (0.635).

| | INCHES | | MILLIN | IETERS |
|-----|--------|-------|--------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.385 | 0.395 | 9.78 | 10.03 |
| В | 0.385 | 0.395 | 9.78 | 10.03 |
| С | 0.165 | 0.180 | 4.20 | 4.57 |
| Е | 0.090 | 0.110 | 2.29 | 2.79 |
| F | 0.013 | 0.019 | 0.33 | 0.48 |
| G | 0.050 | BSC | 1.27 | BSC |
| Н | 0.026 | 0.032 | 0.66 | 0.81 |
| J | 0.020 | | 0.51 | |
| K | 0.025 | | 0.64 | |
| R | 0.350 | 0.356 | 8.89 | 9.04 |
| U | 0.350 | 0.356 | 8.89 | 9.04 |
| ٧ | 0.042 | 0.048 | 1.07 | 1.21 |
| W | 0.042 | 0.048 | 1.07 | 1.21 |
| Х | 0.042 | 0.056 | 1.07 | 1.42 |
| Υ | | 0.020 | - | 0.50 |
| Z | 2° | 10° | 2° | 10 ° |
| G1 | 0.310 | 0.330 | 7.88 | 8.38 |
| K1 | 0.040 | | 1.02 | |

PACKAGE DIMENSIONS

SOEIAJ-16 CASE 966-01 **ISSUE A**



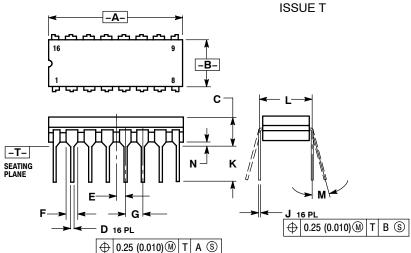
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI

- NOTES:

 1 DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS DI AND E DO NOT INCLUDE MOLD
 FLASH OR PROTRUSIONS AND ARE MEASURED
 AT THE PARTING LINE. MOLD FLASH OR
 PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
 PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD
 TO BE 0.46 (0.018).

| | MILLIN | IETERS | INC | HES | | |
|----------------|---------|--------|-------|-------|--|--|
| DIM | MIN MAX | | MIN | MAX | | |
| Α | | 2.05 | | 0.081 | | |
| A ₁ | 0.05 | 0.20 | 0.002 | 0.008 | | |
| b | 0.35 | 0.50 | 0.014 | 0.020 | | |
| C | 0.10 | 0.20 | 0.007 | 0.011 | | |
| D | 9.90 | 10.50 | 0.390 | 0.413 | | |
| Е | 5.10 | 5.45 | 0.201 | 0.215 | | |
| е | 1.27 | BSC | 0.050 | BSC | | |
| HE | 7.40 | 8.20 | 0.291 | 0.323 | | |
| L | 0.50 | 0.85 | 0.020 | 0.033 | | |
| LE | 1.10 | 1.50 | 0.043 | 0.059 | | |
| M | 0 ° | 10 ° | 0 ° | 10° | | |
| Q ₁ | 0.70 | 0.90 | 0.028 | 0.035 | | |
| Z | | 0.78 | | 0.031 | | |

CDIP-16 **L SUFFIX** CERAMIC DIP PACKAGE CASE 620-10 **ISSUE T**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

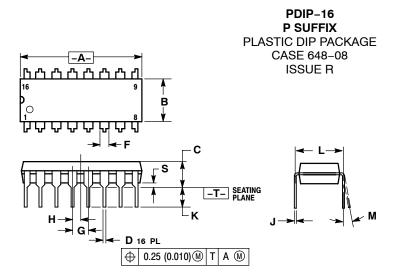
 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEAD WHEN FORMER DANNING.

- FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

| | INC | HES | MILLIN | IETERS |
|-----|-------|-------|----------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.750 | 0.785 | 19.05 | 19.93 |
| В | 0.240 | 0.295 | 6.10 | 7.49 |
| С | | 0.200 | | 5.08 |
| D | 0.015 | 0.020 | 0.39 | 0.50 |
| E | 0.050 | BSC | 1.27 | BSC |
| F | 0.055 | 0.065 | 1.40 | 1.65 |
| G | 0.100 | BSC | 2.54 BSC | |
| Н | 0.008 | 0.015 | 0.21 | 0.38 |
| K | 0.125 | 0.170 | 3.18 | 4.31 |
| L | 0.300 | BSC | 7.62 | BSC |
| M | 0 ° | 15° | 0° | 15° |
| N | 0.020 | 0.040 | 0.51 | 1.01 |

PACKAGE DIMENSIONS



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

| | INCHES | | MILLIN | IETERS |
|-----|-----------|-------|----------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.740 | 0.770 | 18.80 | 19.55 |
| В | 0.250 | 0.270 | 6.35 | 6.85 |
| С | 0.145 | 0.175 | 3.69 | 4.44 |
| D | 0.015 | 0.021 | 0.39 | 0.53 |
| F | 0.040 | 0.70 | 1.02 | 1.77 |
| G | 0.100 BSC | | 2.54 BSC | |
| Н | 0.050 BSC | | 1.27 | BSC |
| J | 0.008 | 0.015 | 0.21 | 0.38 |
| K | 0.110 | 0.130 | 2.80 | 3.30 |
| L | 0.295 | 0.305 | 7.50 | 7.74 |
| M | 0° | 10° | 0° | 10 ° |
| S | 0.020 | 0.040 | 0.51 | 1.01 |

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